



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

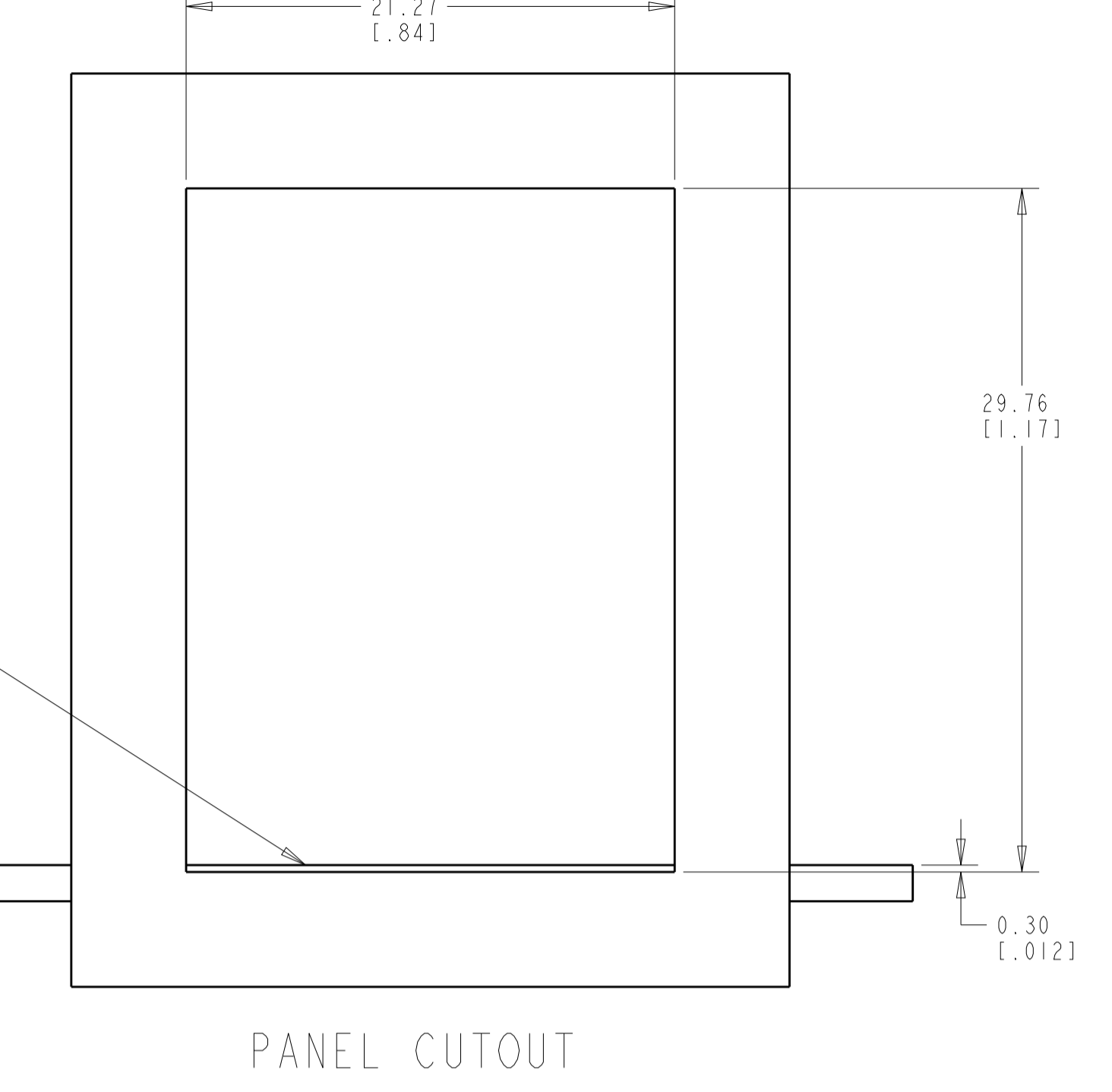
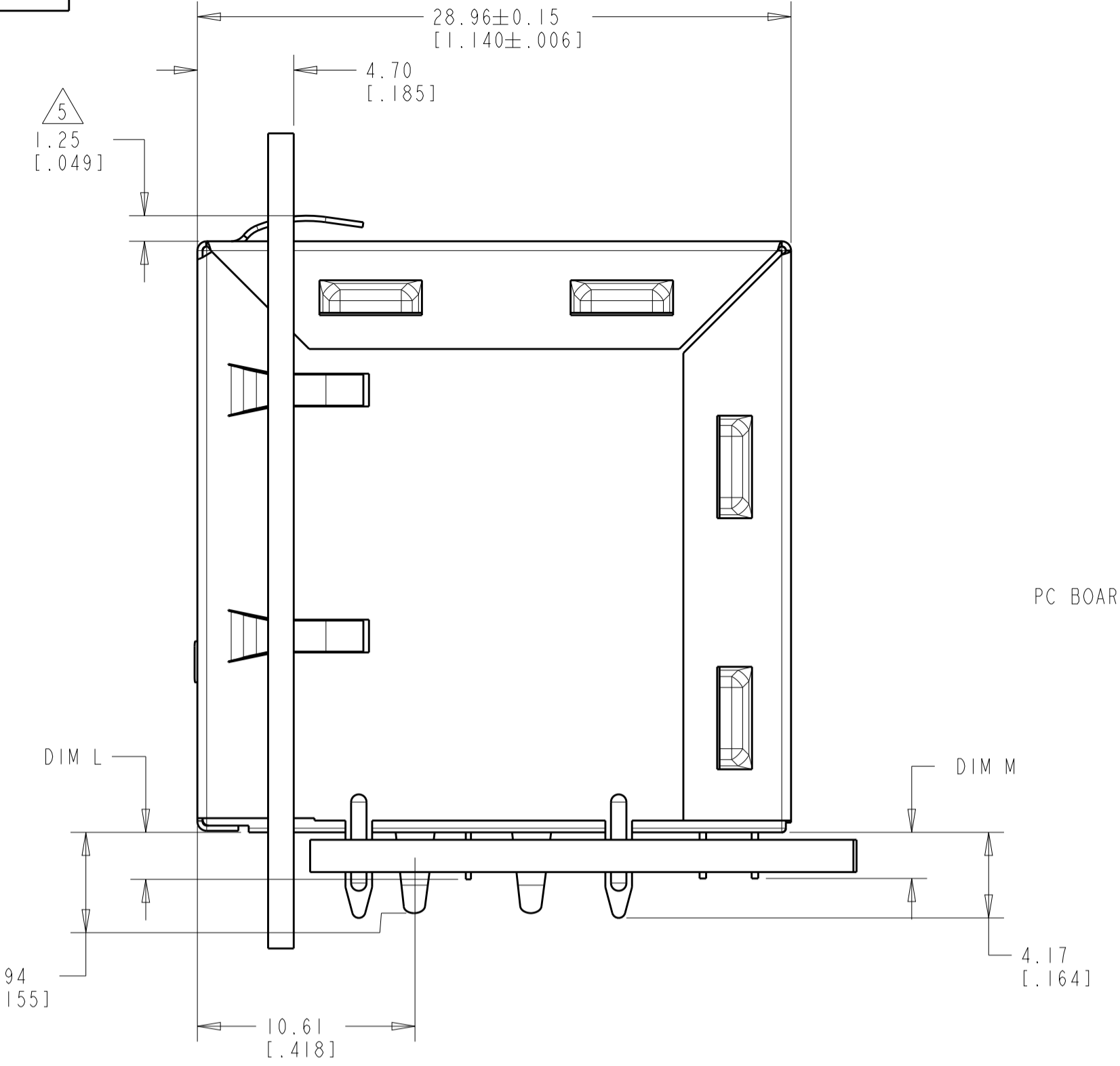
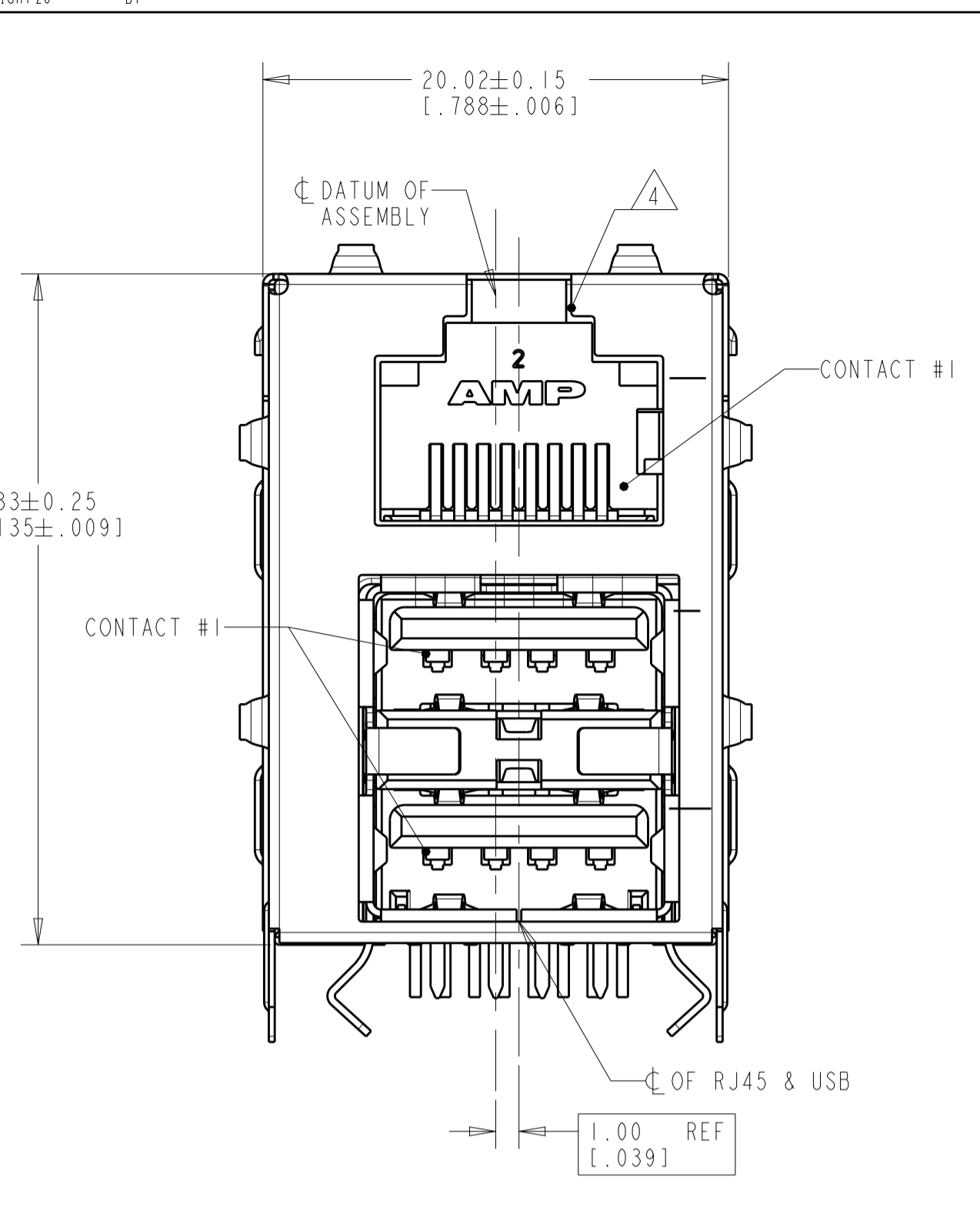
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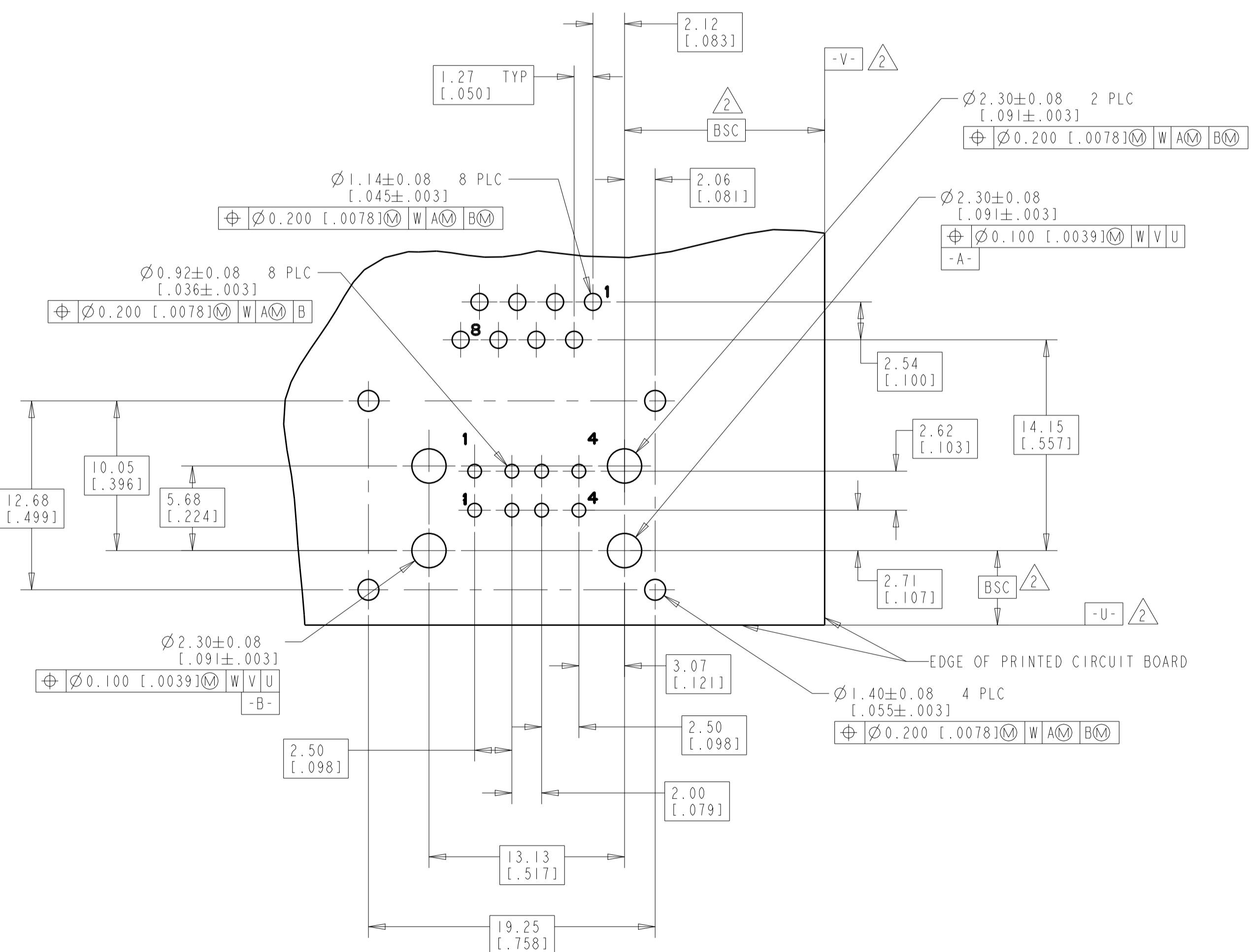
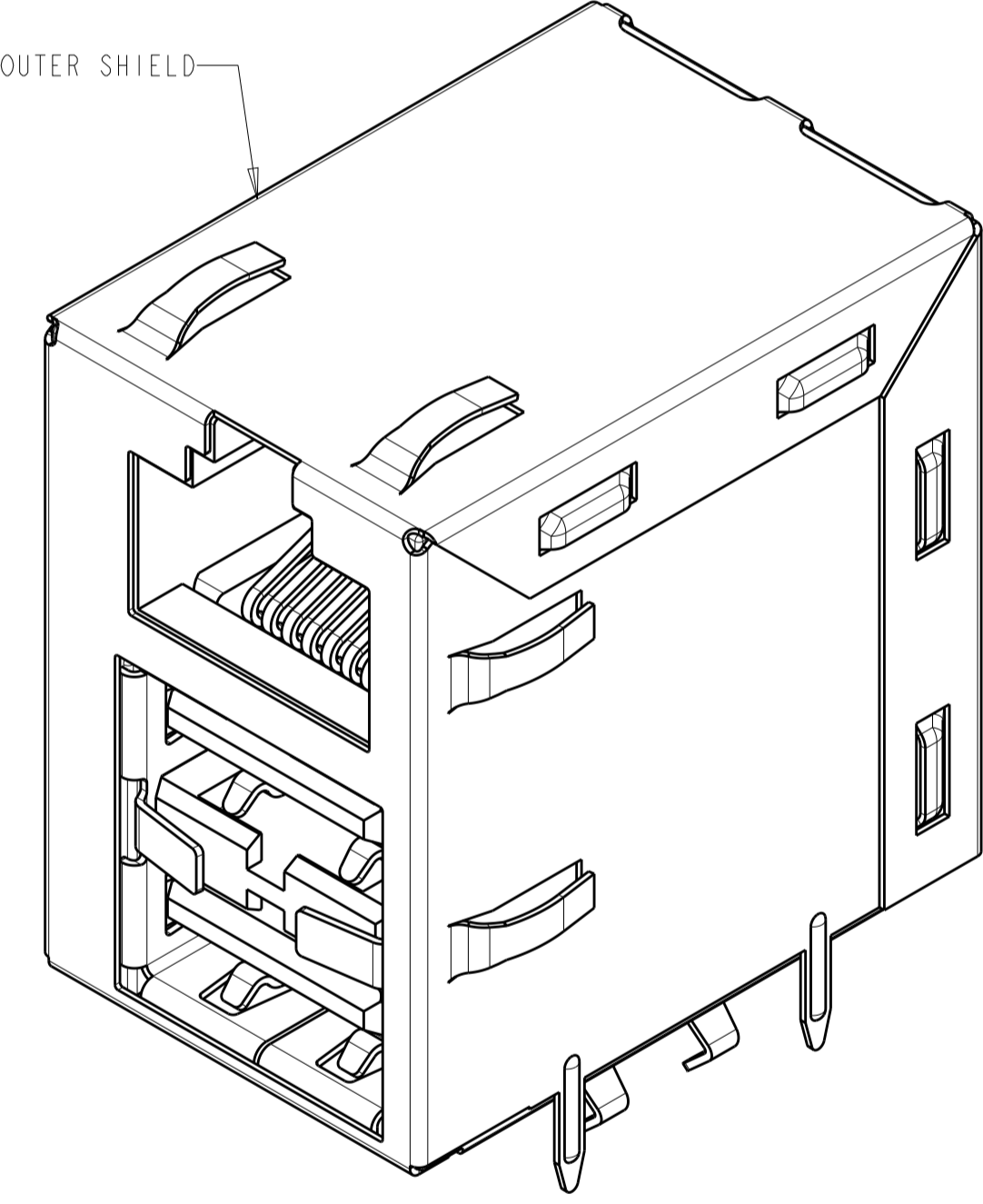


REVISIONS				
P.	LTN.	DESCRIPTION	DATE	APP'D.
D		REVISED PER ECO-16-016643	17NOV2016	LL SH
E		ECO-16-018208	19DEC2016	LL SH



PANEL CUTOUT SHOWN IN VIEW FOR DIMENSIONAL LOCATION

1. MATERIAL:
- HOUSING: PLASTIC HOUSINGS: UL94V-0/5V THERMOPLASTIC, COLOR: BLACK  
 TERMINAL: USB: 0.251±0.013 THICK PHOSPHOR BRONZE PLATED WITH 1.27µm NICKEL. IN LOCALIZED GOLD PLATE AREA 0.076µm MIN GOLD OVER 0.76µm MIN PALLADIUM-NICKEL IS ADDED OVER NICKEL UNDERPLATE. IN SOLDER AREA 3.8µm MIN TIN IS ADDED OVER NICKEL UNDERPLATE.  
 RJ45: 0.318 THICK PHOSPHOR BRONZE PLATED WITH 1.27µm MIN THICK NICKEL. IN LOCALIZED GOLD PLATE AREA 1.27µm MIN THICK GOLD IS ADDED OVER NICKEL UNDERPLATE. IN SOLDER AREA 3.8µm MIN TIN IS ADDED OVER NICKEL UNDERPLATE.  
 SHIELD: OUTER: 0.254 THICK COPPER-ZINC ALLOY PREPLATED WITH TIN 2µm TO 3.8µm THICK.  
 INNER: 0.318 THICK COPPER-ZINC ALLOY PREPLATED WITH TIN 2µm TO 3.8µm THICK.  
 USB: 0.318 THICK PHOSPHOR-BRONZE PREPLATED WITH 5.1µm MIN TIN
- 2 DATUM AND BASIC DIMENSION ESTABLISHED BY CUSTOMER
  - 3 RECOMMENDED PC BOARD THICKNESS OF 1.57[0.062] FOR 1888371-1. RECOMMENDED PC BOARD THICKNESS OF 2.38[0.093] FOR 1888371-2.
  - 4 RJ45 JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS, PART 68 SUBPART F
  - 5 BEFORE INSERTION IN PANEL CUTOUT



RECOMMENDED PCB LAYOUT

DIM L	DIM M	PART NUMBER
2.85 ±0.25 [0.112 ±0.009]	2.85 ±0.25 [0.112 ±0.009]	1888371-2
2.29 ±0.25 [0.090 ±0.009]	2.25 ±0.25 [0.089 ±0.009]	1888371-1

THIS DRAWING IS A CONTROLLED DOCUMENT.

OWN: B. H/L.A.MAYER 16FEB2006  
 CH: J.WESTMAN 16FEB2006  
 APP'D: S.FLICKINGER 16FEB2006

DIMENSIONS: mm [INCHES]

TOLERANCES UNLESS OTHERWISE SPECIFIED:

0 PLC	±
1 PLC	±0.131[0.005]
2 PLC	±
3 PLC	±
4 PLC	±
ANGLES	±1°

MATERIAL: SEE NOTE 1  
 FINISH: SEE NOTE 1

WEIGHT: -  
 CUSTOMER DRAWING

NAME: ASSEMBLY, RJ-45 MODULAR JACK OVER STACKED USB RECEPTACLE

SIZE: A1  
 CAGE CODE: 00779  
 DRAWING NO: 1888371

RESTRICTED TO: -  
 SCALE: 4:1  
 SHEET: 1 OF 1  
 REV: E